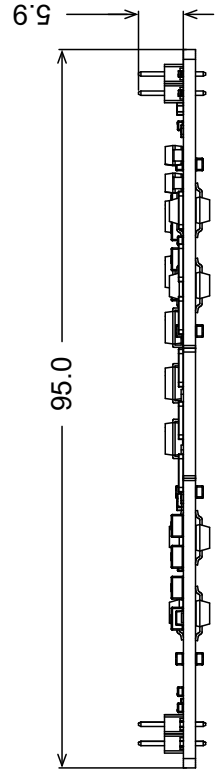
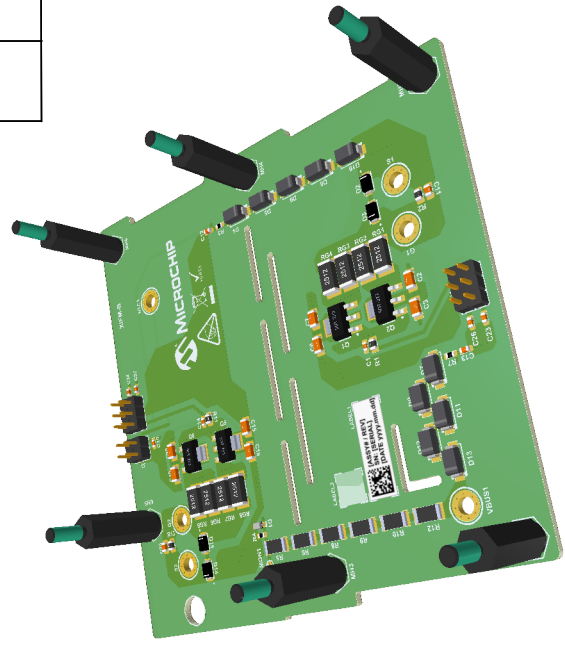
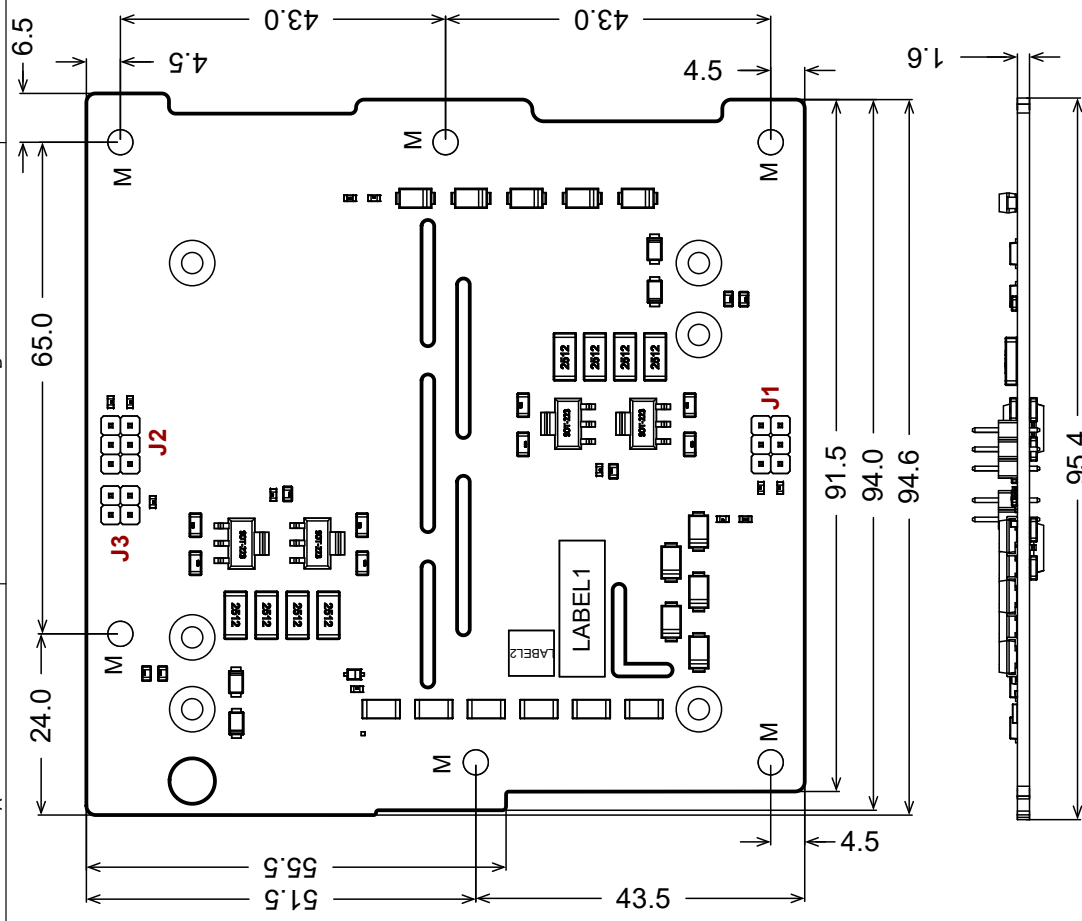


VERSION CONTROL	
VER	INITIAL
1	VG
	FINAL RELEASE



INTERCONNECTS		
REF	TYPE	MFG PART NUMBER
J1, J2	Header	TSW-103-23-F-D
J3	Header	HTSW-102-07-G-D

<b>NOTES</b> TOLERANCES UNLESS OTHERWISE SPECIFIED X = ±0.5 XX = ±0.25 XXX = ±0.13 BOARD THICKNESS BOARD OUTLINE 2.28 ± 0.254 X = ±0.1 COMPONENT HOLES AND MOUNTING HOLES ±0.381 ± 0.076 ±0.381 ± 0.127 HOLE M = LGBT MOUNTING HOLE HOLE F = FIXING HOLES	
<b>DRWN BY</b> Vipin G	<b>DATE</b> 8/24/2023
<b>APPD BY</b> **	<b>DATE</b> 8/24/2023

<b>MICROCHIP</b> Microchip Technology Inc. 2025 Washington Avenue Philadelphia, PA 19146	
<b>TITLE</b> XIFM LinPak HV100 Buffer Board	<b>SCALE</b> 1:1
<b>SIZE</b> A4	<b>PART NO</b> XIFM-B
<b>VER</b> 1	<b>SHEET</b> 1 of 1